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Compiance

VOLTAGE RANGE 150 to 200 Volts CURRENT 5.0 Amperes



SMB

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any * Weight: 0.093 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwies specified. Single phase half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

P/N(MARK)		SS515B	SS520B	UNITS
Maximum Recurrent Peak Reverse Voltage		150	200	V
Maximum RMS Voltage		105	140	V
Maximum DC Blocking Voltage		150	200	V
Maximum Average Forward Rectified C	Current			
at TL=100°C		5.0		А
Peak Forward Surge Current, 8.3 ms single half sine-wave				
superimposed on rated load (JEDEC method)		120		А
Maximum Instantaneous Forward Voltage at 5.0A		0.92		V
Maximum DC Reverse Current	Ta=25°C		0.02	mA
at Rated DC Blocking Voltage	Ta=100°C		2	mA
Typical Junction Capacitance (Note1)		380		PF
Typical Thermal Resistance RθJL(Note 2)		12		°C/W
Operating Temperature Range T _J		-65 — +150		°C
Storage Temperature Range Tsrg		-65 — +150		°C

NOTES:

- 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
- 2. Thermal Resistance Junction to Lead Vertical PC Board Mounting 0.375"(9.5mm) Lead Length.

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RATING AND CHARACTERISTIC CURVES (SS515B THRU SS520B)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

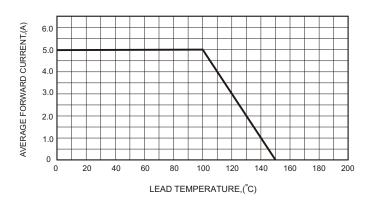


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

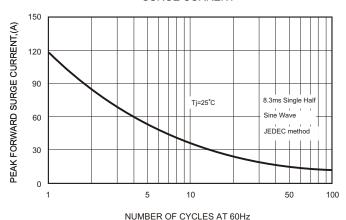


FIG.4-TYPICAL JUNCTION CAPACITANCE

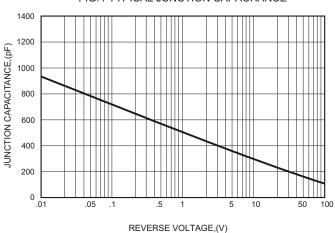


FIG.2-TYPICAL FORWARD

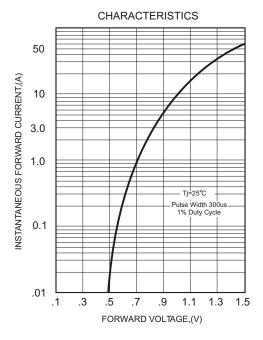
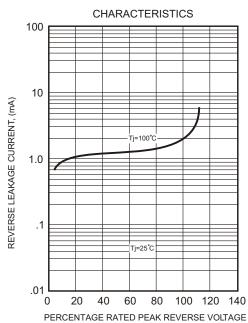
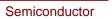


FIG.5 - TYPICAL REVERSE

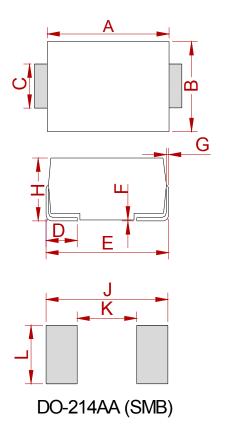








PACKAGE MECHANICAL DATA



		Dimensions			
Ref.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
Α	4.25	4.75	0.167	0.187	
В	3.30	3.94	0.130	0.155	
С	1.85	2.21	0.073	0.087	
D	0.76	1.52	0.030	0.060	
Е	5.08	5.59	0.200	0.220	
F	0.051	0.203	0.002	0.008	
G	0.15	0.31	0.006	0.012	
Н	2.11	2.44	0.083	0.096	
J	6.80		0.270		
K		2.60		0.100	
L	2.40		0.090		

REEL SPECIFICATION

P/N	PKG	QTY
SS515B THRU SS520B	SMB	3000





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